10/611,395

L Number	Hits	Search Text	DB	Time stamp
1	2016	((438/455) or (257/777)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 17:22
2	1925	(((438/455) or (257/777)).CCLS.) and @ad<20030630	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 17:22
-	26	(("5102821") or ("5373184") or ("5413952") or ("5849627") or ("5866469") or ("5882532") or ("20020160582") or ("20020076902") or ("20020001920") or ("20020195673") or ("6406636") or ("6380629") or ("20030060020")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 14:58
-	0	(wafer adj bond$3) and @ad<20030630 and ((native adj oxide) near4 remov$3) and ((pad terminal electrode) near3 (cu copper)) and (electroplat$3 electroless) and (conductive near3 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 15:00
-	0	(wafer adj bond$3) and @ad<20030630 and ((native adj oxide) near4 remov$3) and ((pad terminal electrode) near3 (cu copper)) and (electroplat$3 electroless)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 15:00
-	22	@ad<20030630 and ((native adj oxide) near4 remov$3) and ((pad terminal electrode) near3 (cu copper)) and (electroplat$3 electroless)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/21 17:22

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